**GOMACTech 2007 Technical Session Proposal and Information Form**

| | |
|---|---|
| **Session Title:** | Technologies for Sensor C-SWAP Reduction |
| **Session Abstract (250 words):** | Enabling technologies are being developed to address the challenging cost, size, weight, and power (C-SWAP) requirements of future sensors. These low cost, multi-function sensors will have novel architectures, require less prime power, and be highly manufacturable. To achieve C-SWAP reduction, low areal density muli-layer substrates using "RF on Flex", plastic and Liquid Crystal Polymer (LCP) packaging, and high performance GaAs, SiGe, and antemonide based MMICs are being designed, fabricated, and tested. This session will present some of the latest work addressing technologies for sensor C-SWAP reduction. |

| | |
|---|---|
| **Session Champion:** | Chris Lesniak |
| **Phone:** | 937-255-3801 X3488 |
| **Email:** | Christopher.lesniak@wpafb.af.mil |

| | |
|---|---|
| **Session Organizer:** | Chris Lesniak |
| **Phone:** | |
| **Email:** | |

| | |
|---|---|
| **Session Chair:** | Bradley Paul |
| **Phone:** | 937-255-4557 X3442 |
| **Email:** | Bradley.paul@wpafb.af.mil |

| | |
|---|---|
| **Session Co-Chair:** | Chris Lesniak |
| **Phone:** | |
| **Email:** | |

| | **Invited Paper Title** | **Author** | **Affiliation** |
|---|---|---|---|
| **1** | Highly Integrated T/R MMICs | Steve Nelson | REMEC |
| **2** | Receiver on a Chip | Tony Quach | AFRL |
| **3** | X-Band Tile Development | Anthony Jacomb-Hood<br>J-P Lanteri | Lockheed Martin<br>M/A-COM |
| **4** | Plastic Packaging for Space Applications | J-P Lanteri | M/A-COM |

Paper tiles are not final at this time.
Other Possible papers:

**5. ISIS – Northrop Grumman**
**6. LCP Packaging – REMEC**
**7. 3D IC – AFRL & partners**